**NGUYEN HUU ANH**

Phone: +84 941 980 911

Email: [huuanhhng@gmail.com](mailto:huuanhhng@gmail.com)

Address: 454 Vo Chi Cong, District 9, HCMC

**Brief introduction** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

I am a software engineer with robust problem-solving skills and hands-on experience in designing and creating software in the field of semiconductor industry, special Wire Bonders machine (making chip).

**Work experience** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**Shinkawa Vietnam Co. Ltd, Ho Chi Minh City** |www.shinkawa.com

***> Software Engineer*** ***(R&D department)*,** November 2016 - October 2020

**Wok overview:**

* Design and implement software functions, software components.
* Study and improvement existing feature to matching with Customer’s requirement.
* Supplementary document for software design, user manual.

**Product:** Wire Bonders machine (UTC-5000NeoCu Super, UTC-5000Super and UTC-5100 machine).

**Description:** Wire bonding is the process of creating electrical interconnections between semiconductors (or other integrated circuits) and silicon chips using bonding wires. Shinkawa commands the top global share as a manufacturer of bonders. Wire Bonders of Shinkawa is able to automatically bonding with high accuracy; inspecting bond point and bond wire by camera and electric. Many Wire Bonders are controlled by central host via S-Brain and S-Link network.

**Technology:** C/C++, MFC, SECS, RTOS, SQL…

**Career features highlight:**

* Strip-mapping function of two-dimensional barcode (2D matrix code) using SEMI G84-0303 (specification for Strip-mapping protocol).
* SimLoop function reduces parameter setup time with automated loop shape optimization. Improving UPH by about 7% with built-in Overdrive mode.
* Automatic Bond Level Acquisition function automatically sets bond levels at start bonding. It eliminates bond levels setup time after Capillary change.

**Product:** Bump Bonder SBB-5200 machine (based on Wire Bonder model UTC-5000).

* Design and implement function to enable the Operator to run production with Wafers whose 2D codes have been read with a handheld barcode reader.

**Product:** CAD Data Making tool for Wire Bonders (hereinafter, CDMT).

**Description:** CDMT works as an AutoCAD plug-in, allowing the bond coordinate data importable to Wire Bonders from CAD drawing. This tool enables user to create product-type data quickly and accurately without the burden of newly creating product-type data in Wire bonders.

**Technology:** HTML, VB.NET, ArxObject and AutoLisp languages.

**Responsibility:** Integration softwarefor AutoCAD from 2016 to 2020 on both Windows 7/10 64-bit (previously only AutoCAD 2015 and earlier).

**Shinkawa Ltd, Tokyo - Japan** |www.shinkawa.com

***> Software Engineer (R&D department)*,** October 2019 - November 2019

**Work overview**

* Trained in about Wafer Bump Bonders machine (SBB-5200 operations and source code).
* Design and implement software components for Upgrade Wire Bonders machine run on Windows 10 IOT platform.

**Personal project**

* Personal Web Server by using a raspberry pi 3b+ single-board computer. The purpose is to store, selectively share and publish data information. Thinks I used: raspberry pi 3b+, PHP7, HTML, No-IP Dynamic DNS. Link: [*http://nha.sytes.net*](http://nha.sytes.net)

**Skills** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**Technical:**

* Experience in C++ Object-Oriented Programing, C/C++, MFC Framework.
* Experience in compilation, testing and debugging the code using Visual Studio IDE.
* Basic knowledge in Python, PyQt5 design.

**Dev tools:** Visual Studio, Visual SourceSafe, TFS, Git, Qt Creator, make file, Tera term.

**Soft skills:**

* Strong problem solving and root cause analysis skills.
* Ability to self-study new technical.
* Having passion to work, willing to relocate.

**Languages:** Ability to read and write English technical documents.

**Education** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**HCMC INDUSTRY AND TRADE COLLEGE**, September 2011 – July 2014

*Bachelor of Information Technology.*

**Interests** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

DIY programing, playing guitar and football.